



(51) International Patent Classification:

H01L 31/167 (2006.01) *G01S 17/02* (2006.01)
H01L 31/0232 (2006.01) *H01L 25/16* (2006.01)

(21) International Application Number:

PCT/CH2012/000159

(22) International Filing Date:

10 July 2012 (10.07.2012)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

61/509,346 19 July 2011 (19.07.2011) US

(71) Applicant (for all designated States except US): **HEP-TAGON MICRO OPTICS PTE. LTD.** [SG/SG]; 87 Defu Lane 10 #04-00, Singapore 539219 (SG).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **RUDMANN, Hartmut** [DE/CH]; Rütliwiesstrasse 20, CH-8645 Jona (CH).
ROSSI, Markus [CH/CH]; Rütliwiesstrasse 24, CH-8645 Jona (CH).

(74) Agent: **FREI PATENTANWALTSBURÖ AG**; Postfach 1771, CH-8032 Zürich (CH).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM,

AO, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

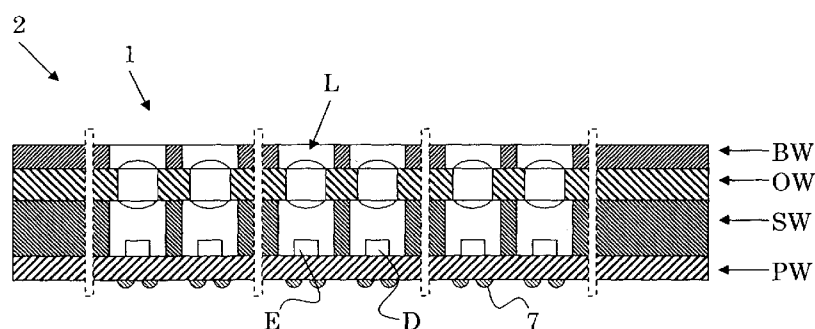
Published:

- with international search report (Art. 21(3))
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments (Rule 48.2(h))

(88) Date of publication of the international search report:

18 July 2013

(54) Title: OPTO -ELECTRONIC MODULES AND METHODS OF MANUFACTURING THE SAME

**Fig. 4**

(57) Abstract: The method for manufacturing opto-electronic modules (1) comprises • a) providing a substrate wafer (PW) on which a multitude of detecting members (D) are arranged; • b) providing a spacer wafer (SW); • c) providing an optics wafer (OW), said optics wafer comprising a multitude of transparent portions (t) transparent for light generally detectable by said detecting members and at least one blocking portion (b) for substantially attenuating or blocking incident light generally detectable by said detecting members; • d) preparing a wafer stack (2) in which said spacer wafer (SW) is arranged between said substrate wafer (PW) and said optics wafer (OW) such that said detecting members (D) are arranged between said substrate wafer and said optics wafer. Preferably, a multitude of emission members (E) for emitting light generally detectable by said detecting members (D) is arranged on said substrate wafer (PW) such that a multitude of neighboring emission members and detecting members are present on said substrate wafer. Single modules (I) can be obtained by separating said wafer stack (2) into a multitude of separate modules (I). The manufacturing method may be applied for the manufacture of proximity sensors.